



Material Content Data Sheet



Sales Product Name	BCX 53-10 H6327			Issued		1. August 2018		
MA#	MA001216734							
Package	PG-SOT89-4-3			Weight*		53.17 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.01		83	
	noble metal	gold	7440-57-5	0.017	0.03		322	
	inorganic material	silicon	7440-21-3	0.209	0.39	0.43	3927	4332
leadframe	inorganic material	silicon	7440-21-3	0.005	0.01		95	
	non noble metal	titanium	7440-32-6	0.025	0.05		474	
	non noble metal	chromium	7440-47-3	0.076	0.14		1423	
	non noble metal	copper	7440-50-8	25.112	47.23	47.43	472308	474300
wire	non noble metal	copper	7440-50-8	0.049	0.09	0.09	924	924
encapsulation	organic material	carbon black	1333-86-4	0.268	0.50		5040	
	plastics	epoxy resin	-	4.019	7.56		75599	
	inorganic material	silicondioxide	60676-86-0	22.509	42.34	50.40	423352	503991
leadfinish	non noble metal	tin	7440-31-5	0.801	1.51	1.51	15071	15071
plating	noble metal	silver	7440-22-4	0.073	0.14	0.14	1382	1382
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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